PATENT ASSIGNMENT

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SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT

CONVEYING PARTY DATA

Name	Execution Date
Deok-Hyun KIM	11/23/2010
Jae-Myung KIM	11/23/2010
Kyu-Nam JOO	11/23/2010
So-Ra LEE	11/23/2010
Jong-Hee LEE	11/23/2010
Young-Su KIM	11/23/2010
Gu-Hyun CHUNG	11/23/2010
Beom-Kwon KIM	11/23/2010

RECEIVING PARTY DATA

Name:	Samsung SDI Co., Ltd.	
Street Address:	428-5, Gongse-dong, Giheung-gu	
City:	Yongin-si, Gyeonggi-do	
State/Country: REPUBLIC OF KOREA		

PROPERTY NUMBERS Total: 1

Property Type	Number
Application Number:	12957193

CORRESPONDENCE DATA

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501365340 REEL: 025414 FRAME: 0607

PATENT

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NAME OF SUBMITTER:	Christopher Sweeney
Total Attachments: 3 source=ExecutedAssignment#page1.tif source=ExecutedAssignment#page2.tif source=ExecutedAssignment#page3.tif	

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ASSIGNMENT

WHEREAS, I, the undersigned, have invented certain new and useful improvements in a ELECTRODE CONDUCTIVE MATERIAL, ELECTRODE MATERIAL INCLUDING THE CONDUCTIVE MATERIAL, AND ELECTRODE AND LITHIUM BATTERY EACH INCLUDING THE ELECTRODE MATERIAL, the specification of which was executed on even date herewith.

AND WHEREAS, Samsung SDI Co., Ltd., (hereinafter "ASSIGNEE"), with its principal place of business at 428-5 Gongse-dong, Giheung-gu, Yongin-si, Gyeonggi,do, Republic of Korea, desires to acquire the entire right, title, and interest in and to the said improvements with respect to the United States of America, its territories and possessions.

NOW, THEREFORE, in light of good and valuable consideration, the receipt of which is hereby acknowledged, I, the said inventor, do hereby acknowledge that I have sold, assigned, transferred and set over, and by these presents do hereby sell, assign, transfer and set over, unto the said ASSIGNEE, its successors, legal representatives and assigns, the entire right, title, and interest throughout the world in, to and under the said improvements, and the said application and all provisional applications relating thereto, and all divisions, renewals and continuations thereof, and all Letters Patent of the United States which may be granted thereon and all reissues and extensions thereof, and all rights of priority under International Conventions and applications for Letters Patent which may hereafter be filed for said improvements in any country or countries foreign to the United States, and all Letters Patent which may be granted for said improvements in any country or countries foreign to the United States and all extensions, renewals and reissues thereof, and I hereby authorize and request the Commissioner of Patents of the United States, and any Official of any country or countries foreign to the United States, whose duty it is to issue patents on applications as aforesaid, to issue all Letters Patent for said improvements to the said ASSIGNEE, its successors, legal representatives and assigns, in accordance with the terms of this instrument.

AND I HEREBY covenant and agree that I will communicate to the said ASSIGNEE, its successors, legal representatives and assigns, any facts known to me respecting said improvements, and testify in any legal proceeding, sign all lawful papers, execute all divisional, continuing and reissue applications, make all rightful oaths and generally do everything possible to aid the said ASSIGNEE, its successors, legal representatives and assigns, to obtain and enforce proper patent protection for said improvements in all countries.

Date:	23/November/2010	Signature: Deck - Hyun KIM
		Name: KIM, Deok-Hyun Address: c/o Samsung SDI Co., Ltd.
		428-5, Gongse-dong, Giheung-gu Yongin-si, Gyeonggi-do, Republic of Kores

PATENT REEL: 025414 FRAME: 0609

Date: _	23/Novamber/2010	Signature: Jae-Hyung KIM
		Name: KIM, Jae-Myung Address: _c/o Samsung SDI Co., Ltd.
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		Tongin-si, Oyoongg-uo, Aupaono or review
Date:	23/ November/2010	Signature: Kyu - Nam Joo
		Name: JOO, Kyu-Nam
		Address: c/o Samsung SDI Co., Ltd.
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Date:	23 / November /2010	Signature: So-Ra US
		Name: LEE, So-Ra
		Address: c/o Samsung SDI Co., Ltd.
×		428-5, Gongse-dong, Giheung-gu Yongin-si, Gyeonggi-do, Republic of Korea
Date:	23/ November/2010	Signature: Jong - Hee LEE
	·	Name: LEE, Jong-Hee
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Date:	23/Novamber/2010	Signature: Young - Su KIH
	•	Name: KIM, Young-Su
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23/November/2010 CHUNG Gu - Hyun Signature: Date: Name: CHUNG, Gu-Hyun Address: c/o Samsung SDI Co., Ltd 428-5, Gongse-dong, Giheung-gu Yongin-si, Gyeonggi-do, Republic of Korea 23/November/2010 Beom-Kwon Signature: Date: Name: KIM, Beom-Kwon Address: c/o Samsung SDI Co., Ltd. 428-5, Gongse-dong, Giheung-gu Yongin-si, Gyeonggi-do, Republic of Korea

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